



PRODUCT/PROCESS CHANGE NOTICE (PCN)

ATTACHMENT 1 - PCN # : A1304-01

PCN Type: Alternate Assembly Location

Data Sheet Change: None. No change in moisture sensitivity level (MSL).

Detail Of Change:

This notification is to advise our customers that IDT is adding Amkor, Philippines (ATP) as an alternate assembly facility for device types LDS6120PVGI and LDS6120PVGI8. Presently, ATP is a qualified assembly facility for SSOP package family.

The material set details of the current Assembly location is shown in the table below. The die attach used at ATP is qualified IDT material. There is no change from the existing qualified lead frame material, lead finish, mold compound and wire for this alternate assembly site.

There is no change to the moisture performance using the assembly material sets as listed in the below table.

Qualified Material Sets, by Assembly Subcontractor

Description	Existing	Add
Assembly Location	PT Unisem, Indonesia	Amkor, Philippines
Assembly Materials	Die Attach: CRM1076NS	Ablestik 8290
	Wire: Au Wire	Au Wire
	Mold Compound: G600	G600
	Lead Frame: Copper Alloy	Copper Alloy
	Plating: Matte 100% Sn	Matte 100% Sn



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Qualification Information and Qualification Data:

Qualification Test Plans and Results :

Qual Plan & Results: The qualification was performed in accordance with JEDEC47 recommended tests

Qual Vehicle: Device 9P946AFLF SSOP-48 (3 lots)

Test Description	Test Method	Test Results (SS / Rej)		
		Lot 1	Lot 2	Lot 3
* HAST - biased (130 °C/85% RH, 100 Hrs)	JESD22-A110	25/0	25/0	25/0
* Temperature Cycle / Condition B (-55 °C to +125 °C, 700 Cyc)	JESD22-A104	25/0	25/0	25/0
* Pressure Cooker (121 °C / 2 ATM, 168 hours)	JESD22-A102	25/0	25/0	25/0
High Temp. Storage Test (150 °C, 1000 Hrs)	JESD22-A103	25/0	25/0	25/0

Note:

* Test requires moisture pre-conditioning sequence per JESD22-A113 prior to stress test